



2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

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- DC to DC converter
- Switching mode converters and inverters
- · General purpose

MECHANICAL DATA

- · Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.029g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
l _F	2	Α			
V_{RRM}	200 - 1000	V			
I _{FSM}	50	Α			
T _{J MAX}	175	°C			
Package	Thin SMA				
Configuration	Single die				











ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	UNIT
Marking code on the device			RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		l _F	2				Α	
Surge peak forward current single half sine t = 8.3ms		I _{FSM} 50					А	
wave superimposed on rated load	t = 1.0ms	IFSM	140					Α
Junction temperature		TJ	-55 to +175				°C	
Storage temperature		T _{STG}	-55 to +175				°C	



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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	R _{OJL}	16	°C/W			
Junction-to-ambient thermal resistance	Reja	73	°C/W			
Junction-to-case thermal resistance	Rejc	14	°C/W			

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 1.0A, T _J = 25°C		0.93	-	V
Forward voltage ⁽¹⁾	RS2DAL	I _F = 2.0A, T _J = 25°C	VF	1.01	1.30	V
	RS2GAL RS2JAL	I _F = 1.0A, T _J = 125°C		0.78	-	V
		I _F = 2.0A, T _J = 125°C		0.88	1.02	V
		I _F = 1.0A, T _J = 25°C		0.98	-	V
	RS2KAL	I _F = 2.0A, T _J = 25°C		1.06	1.30	V
	RS2MAL	I _F = 1.0A, T _J = 125°C		0.83	-	V
		I _F = 2.0A, T _J = 125°C		0.93	1.05	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	1	μA
		T _J = 125°C	I_R	-	40	μA
	RS2DAL RS2GAL		t _{rr}	-	150	ns
Reverse recovery time	RS2JAL	$I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$		-	250	ns
	RS2KAL RS2MAL	- III = 0.23A		-	500	ns
Junction capacitance	RS2DAL RS2GAL RS2JAL	1MHz, V _R = 4.0V	CJ	11	-	pF
canonica capacitation	RS2KAL RS2MAL			10	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
RS2xAL	Thin SMA	14,000 / Tape & Reel			

Notes:

1. "x" defines voltage from 200V(RS2DAL) to 1000V(RS2MAL)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

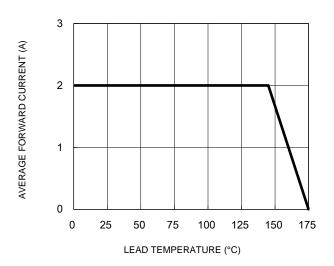


Fig.3 Typical Reverse Characteristics

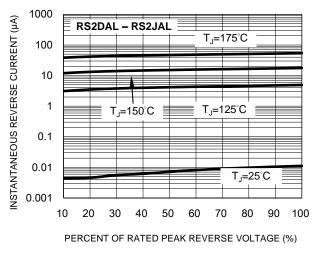


Fig.5 Typical Reverse Characteristics

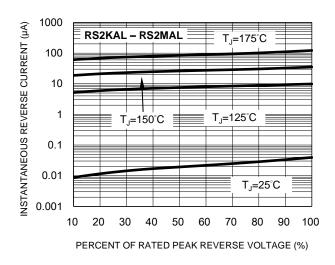


Fig.2 Typical Junction Capacitance

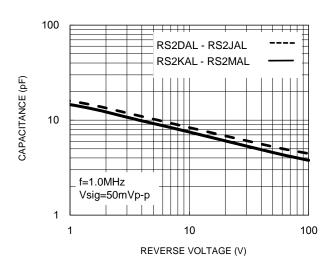


Fig.4 Typical Forward Characteristics

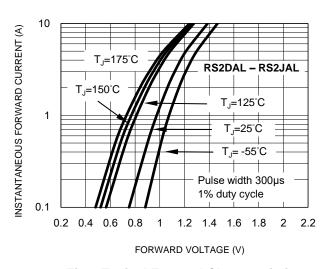
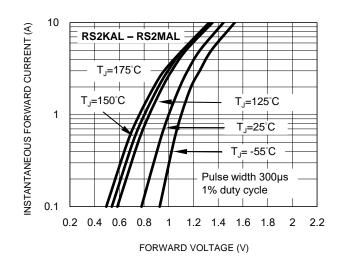


Fig.6 Typical Forward Characteristics

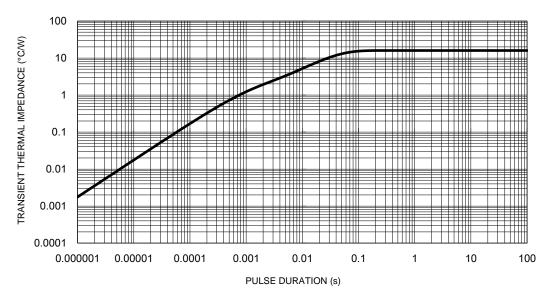


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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

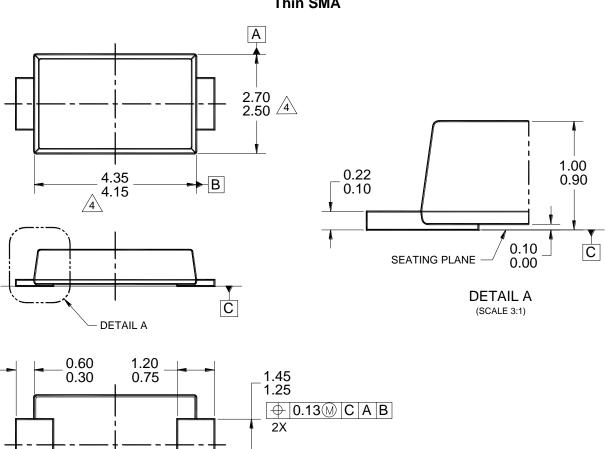
Fig.7 Typical Transient Thermal Impedance

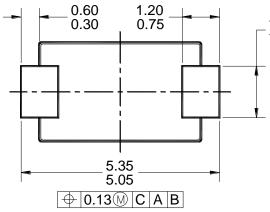


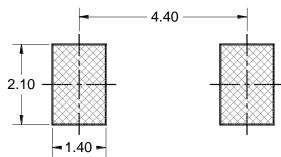


PACKAGE OUTLINE DIMENSIONS

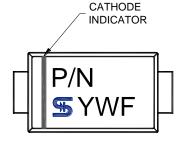
Thin SMA







SUGGESTED PAD **LAYOUT**



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-221, VARIATION AC, ISSUE B.
- MODED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- 5. SUGGESTED PAD LAYOUT IS FOR REFERENCE PURPOSE ONLY.
- 6. DWG NO. REF: HQ2SD07-TSMA-074 REV A.

MARKING DIAGRAM

P/N = MARKING CODE YW = DATE CODE = FACTORY CODE



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